

ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Air)	± 25	kV
	ESD per IEC 61000-4-2 (Contact)	± 20	
P_D	Total Power Dissipation on FR-5 Board (Note 1) @ $T_a=25^\circ\text{C}$	150	mW
T_{OPT}	Operating Temperature	-55~125	$^\circ\text{C}$
T_{STG}	Storage Temperature	-55~150	$^\circ\text{C}$

These ratings are limiting values above which the serviceability of the diode may be impaired

Note 1. FR-5=1.0x0.75x0.62 in.

ELECTRICAL CHARACTERISTICS ($T_{amb}=25^\circ\text{C}$)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{RWM}	Reverse Working Voltage				36	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1\text{mA}$	40			V
I_R	Reverse Leakage Current	$V_{RWM} = 36\text{V}$			5	μA
V_C	Clamping Voltage	$I_{PP} = 1\text{A}$, $t_p = 8/20\mu\text{s}$			55	V
C_J	Junction Capacitance	$V_R = 0\text{V}$, $f = 1\text{MHz}$			28	pF

ELECTRICAL CHARACTERISTICS CURVE

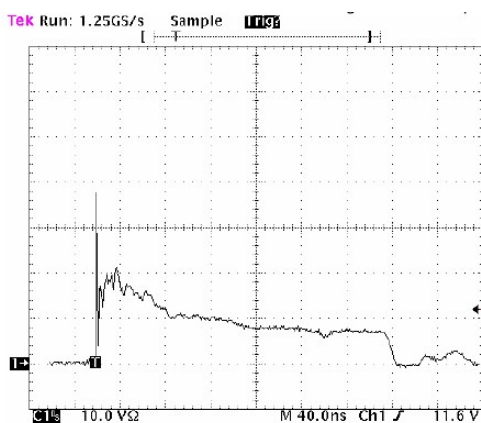


Figure 1. ESD Clamping Voltage Screenshot
Positive 8 kV contact per IEC 61000-4-2

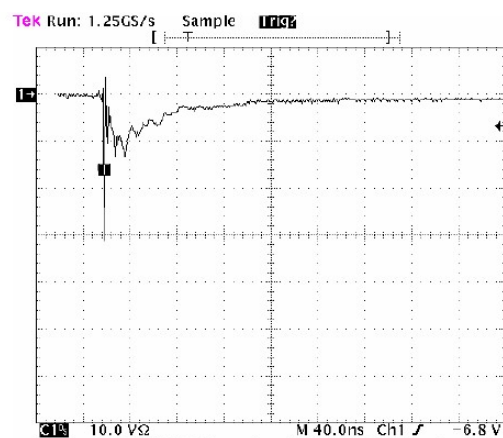
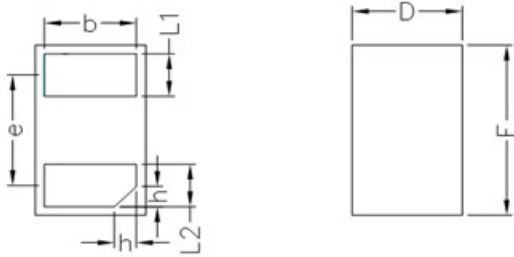


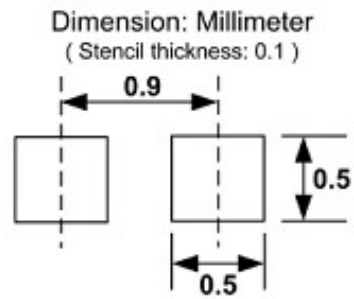
Figure 2. ESD Clamping Voltage Screenshot
Negative 8 kV contact per IEC 61000-4-2

DFN1006 PACKAGE OUTLINE DIMENSIONS



Unit: mm

	MIN	NOM	MAX
D	0.55	0.60	0.65
E	0.95	1.00	1.05
L1	0.20	0.25	0.30
L2	0.20	0.25	0.30
b	0.45	0.50	0.55
e	0.65BSC		
A	0.45	0.50	0.55
h	0.07	0.12	0.17


Soldering Footprint